

AMENDMENT TO THE CLAIMS

The following claim listing replaces all prior listings and versions of the claims:

LISTING OF CLAIMS

1. (Withdrawn) Soldering paste to be disposed between a solder portion formed on a first electrode and a second electrode when the first electrode with the solder portion is soldered to the second electrode, comprising:

liquid basis formed of resin component;

an activator removing oxide film produced on surfaces of the solder portion; and

metal powder including a core metal and a surface metal to cover surfaces of the core metal,

wherein the surface metal has excellent wettability for solder of the solder portion formed on a first electrode, and the core metal is capable of taking the surface metal into itself by dissolving it under heat in a reflow process.

2. (Withdrawn) The soldering paste of claim 1, wherein the core metal is selected from the group of tin, zinc, lead, and indium, and the surface metal includes any one of gold and silver.

3. (Withdrawn) The soldering paste of claim 2, wherein the core metal includes tin or tin-based alloy, and the surface metal includes silver.

4. (Currently amended) A soldering method for soldering a first electrode ~~[[with]]~~ having a solder portion to a second electrode by melting under heat the solder portion of the first electrode, the method comprising ~~[[the]]~~ steps of:

(a) coating [[the]] a soldering paste on at least one of the solder portion of the first electrode and the second electrode, the soldering paste comprising liquid basis formed of resin component, an activator for removing oxide film produced on surfaces of the solder portion, and a flake-like shaped metal powder ~~having metal powder~~ including a core metal and a surface metal ~~to cover surfaces~~ covering a surface of the core metal, wherein the solder portion easily wets and spreads along the surface metal when the solder portion is fluidized ~~on at least one of the solder portion of the first electrode and the second electrode;~~

disposing the soldering paste between the solder portion of the first electrode and the second electrode by (b) positioning the first electrode and the second electrode so that the soldering paste coated in the step (a) is disposed between the solder portion of the first electrode and the second electrode;

(c) letting molten solder come in contact with the second electrode by melting the solder portion under heat and wetting and spreading the molten solder along surfaces of the metal powder included in the soldering paste with guiding the molten solder; and

(d) solidifying the molten solder after the step (c) letting molten solder come in contact with the first electrode and the second electrode, thereby forming a soldered portion which connects the first electrode to the second electrode, wherein:

in the step (a), an amount of the flake-like shaped metal powder in the soldering paste is 1-20 vol %, and

in the step (c), ~~the surface of the core metal is exposed at a portion of letting molten solder come in contact with the second electrode, in the surface~~ of the metal powder which is not in contact with the molten solder, ~~the surface of the core metal is exposed~~ while the surface metal is taken into the core metal by dissolution.

5. (Original) The soldering method of claim 4, wherein the core metal is selected from the group of tin, zinc, lead, and indium, and the surface metal includes any one of gold and silver.

6. (Original) The soldering method of claim 5, wherein the core metal includes tin or tin-based alloy, and the surface metal includes silver.

7. (Cancelled)